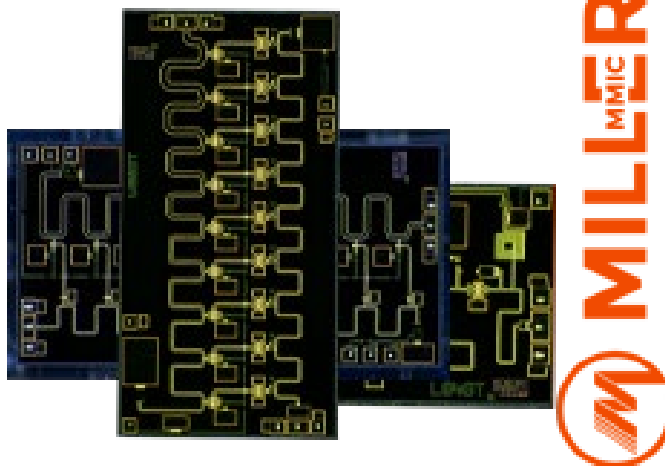


### Features

- Ultra broadband two channel attenuator
- Frequency Range: DC - 40GHz
- 2 Channels with 2 different Attenuation value
- Power Handling: 27dBm
- 50Ω Input and Output Impedance
- Return Loss: 20dB
- Bare Die (QFN Available)
- RoHS & REACH Compliant

### Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- General Purpose



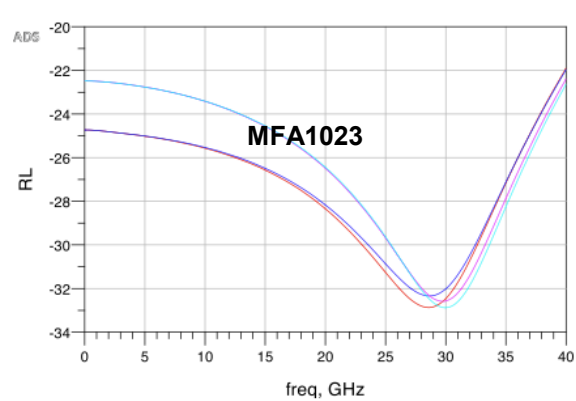
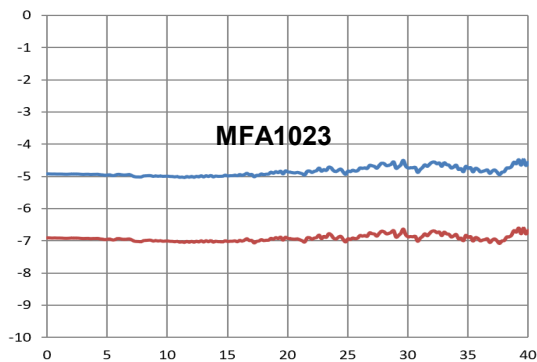
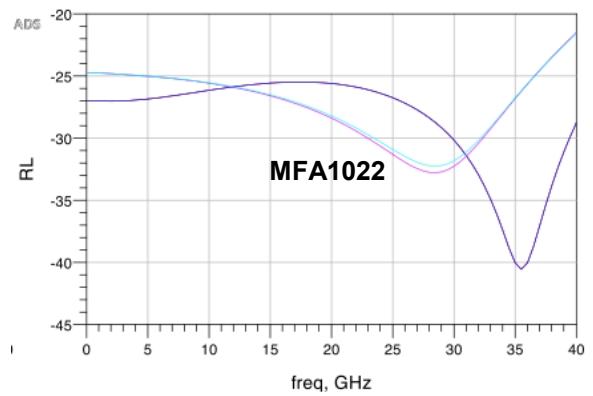
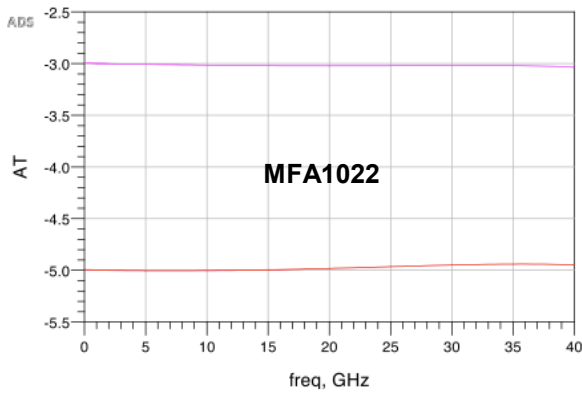
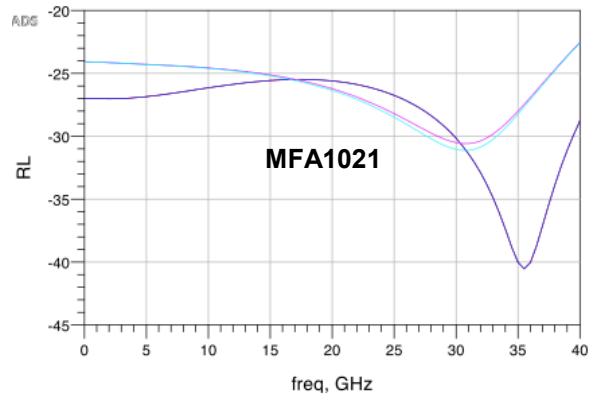
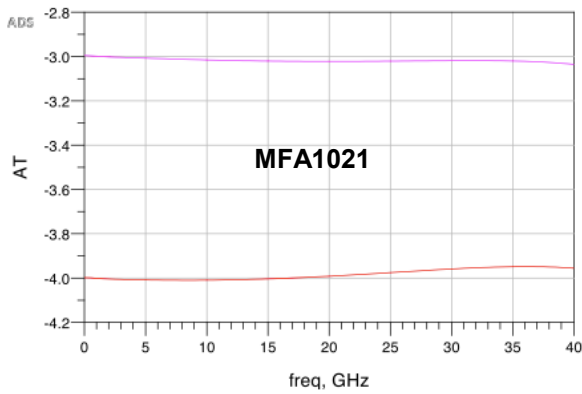
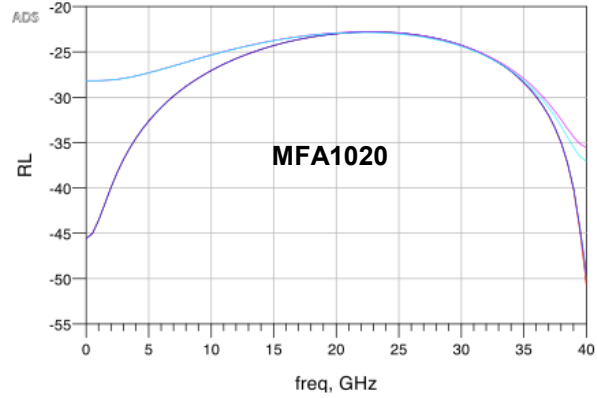
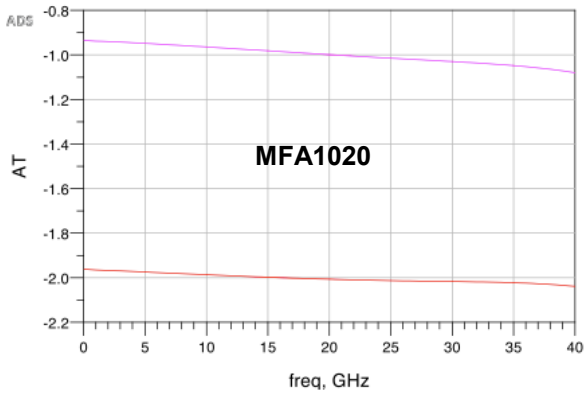
Part No.	Product Description	Frequency (GHz)	Channel	Attenuation (dB)	Power (dBm)	Flatness (dB)	VSWR
MFA1020	2 Channel Fixed Attenuator	DC-40	2	1dB / 2dB	27	±0.3	1.22
MFA1021	2 Channel Fixed Attenuator	DC-40	2	3dB / 4dB	27	±0.3	1.22
MFA1022	2 Channel Fixed Attenuator	DC-40	2	3dB / 5dB	27	±0.3	1.22
MFA1023	2 Channel Fixed Attenuator	DC-40	2	5dB / 7dB	27	±0.3	1.22
MFA1024	2 Channel Fixed Attenuator	DC-40	2	5dB / 8dB	27	±0.3	1.22
MFA1025	2 Channel Fixed Attenuator	DC-40	2	7dB / 8dB	27	±0.3	1.22
MFA1026	2 Channel Fixed Attenuator	DC-40	2	9dB / 10dB	27	±0.35	1.22
MFA1027	2 Channel Fixed Attenuator	DC-40	2	15dB / 20dB	27	±0.4	1.22



### GaAs MMIC Two Channel Series Fixed Attenuator DC-40GHz

MFA1025

GaAs MMIC Two Channel Series Fixed Attenuator DC-40GHz

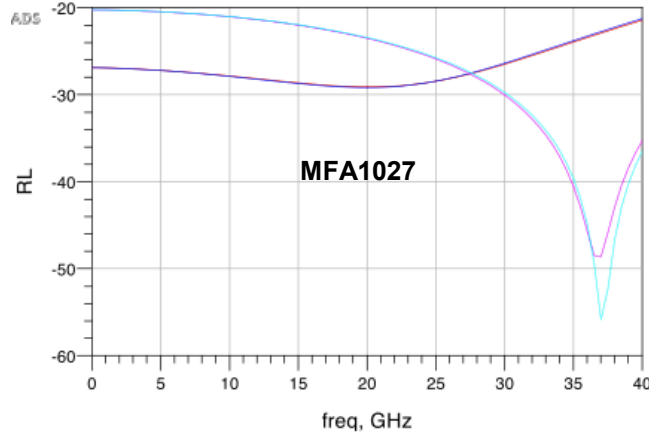
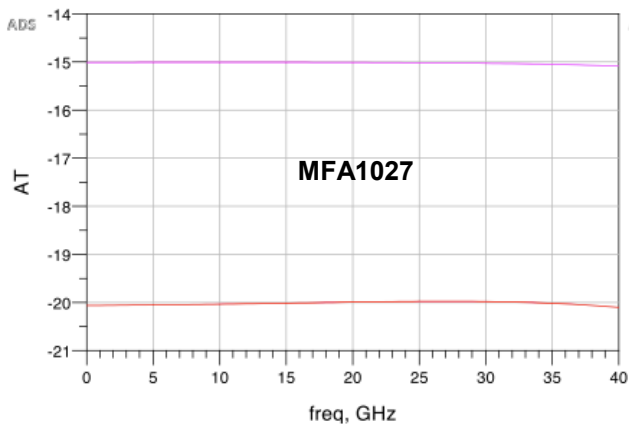
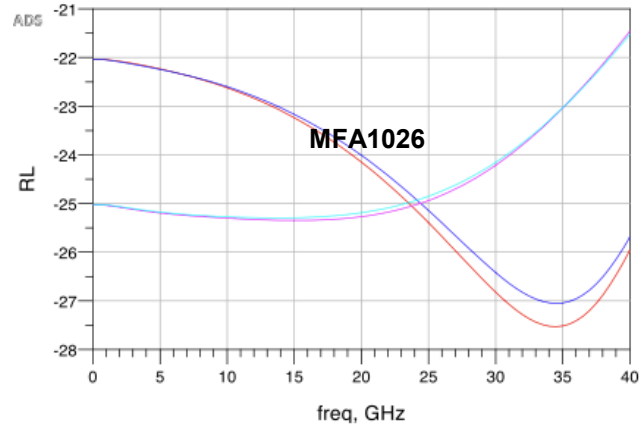
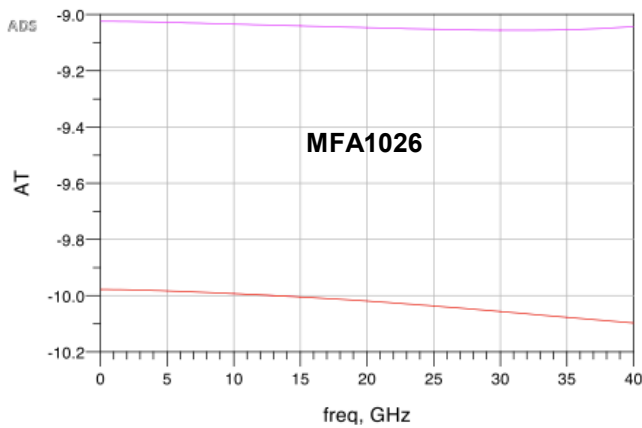
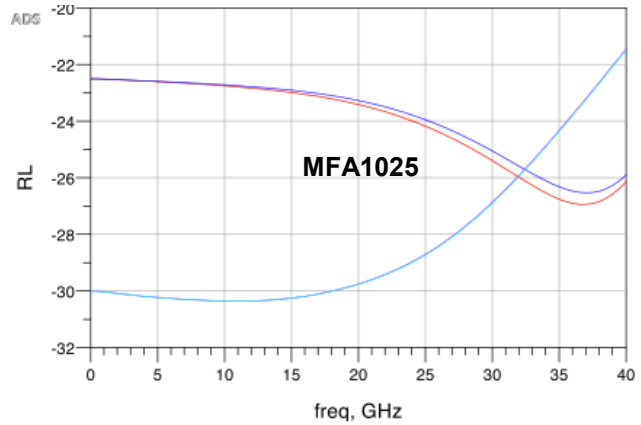
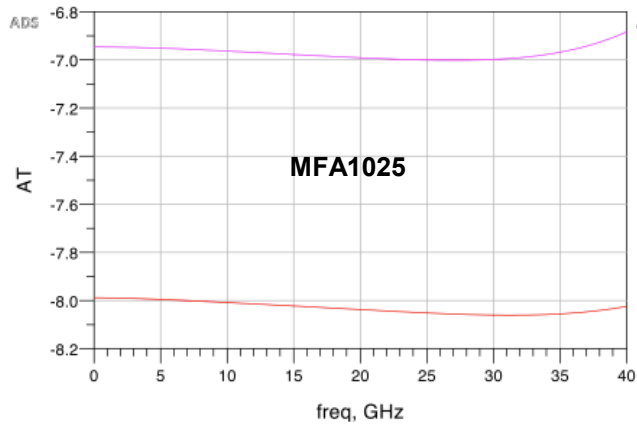
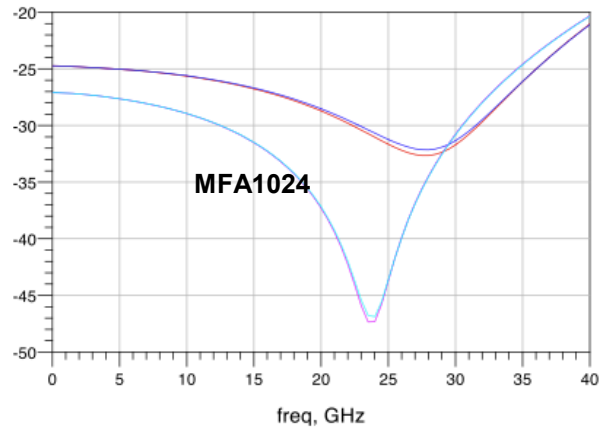
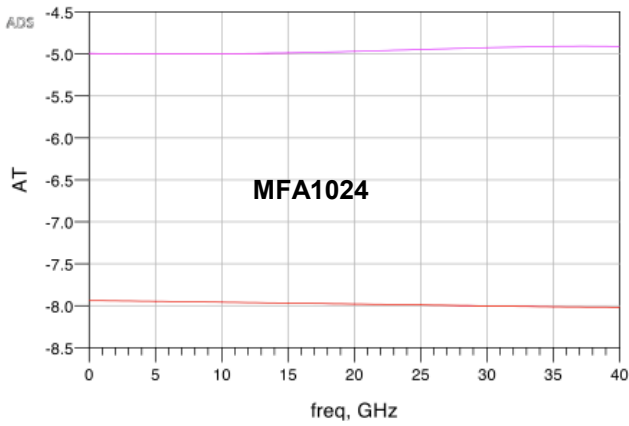




### GaAs MMIC Two Channel Series Fixed Attenuator DC-40GHz

MFA1025

GaAs MMIC Two Channel Series Fixed Attenuator DC-40GHz

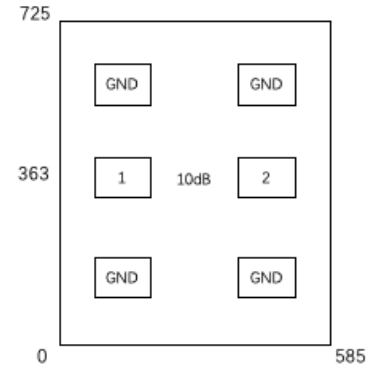




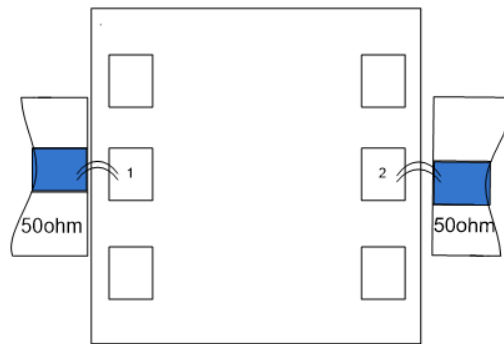
### Outline Drawing:

All Dimensions in  $\mu\text{m}$

Pad	Function	Description
1	RF IN	RF signal input terminal; DC blocking capacitor required.
2	RF OUT	RF signal output terminal; DC blocking capacitor required.
Die bottom	GND	Die bottom must be connected to RF/DC ground.



### Assembly Drawing



#### Notes:

1. Die thickness:  $100\mu\text{m}$
2. Typical bond pad is  $100*100\mu\text{m}^2$
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

#### Maximum Ratings:

1. Maximum input power: +27dBm
2. Operating temperature:  $-55^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$
3. Storage temperature:  $-65^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$

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